

**RESPONSE UNDER 37 C.F.R. § 1.116**

**EXPEDITED PROCEDURE – Art Unit 1733**

Attorney Docket No. 108298636US

Disclosure No. 01-0427.00/US

**Amendments to the Claims:**

Please cancel claims 3-6 and 12-45 without prejudice to pursuing these claims in a divisional, continuation, continuation-in-part, or other application.

1. (Original) A method for assembling microelectronic dies, comprising:  
placing a base die on a substrate in a first die attach head of a die attach machine so that a front side of the base die with bond pads faces toward the substrate and a backside of the base die faces away from the substrate; and  
stacking a first stacked die onto the backside of the base die in a second head of the same die attach machine by dispensing an adhesive onto the backside of the base die and placing a backside of the first stacked die onto the adhesive, wherein the first stacked die is stacked onto the base die before securing the base die to the substrate in a heating cycle.
2. (Original) The method of claim 1, further comprising heating the based die and the first stacked die in a single heating cycle to secure the base die to the substrate and to secure the first stacked die to the base die.
- 3-6. (Cancelled)
7. (Original) The method of claim 1, further comprising automatically transferring the substrate and the base die from the first die attach head to the second die attach head.
8. (Original) The method of claim 1, further comprising transferring the substrate and the base die from the first die attach head to the second die attach head without loading the substrate and the base die into a separate die attach machine.

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9. (Original) The method of claim 1, further comprising placing the base die on the substrate and stacking the first stacked die onto the base die in a single pass through a single die attach machine.

10. (Original) A method for assembling microelectronic dies, comprising:  
preparing a substrate to receive a base die in a first die attach head of a die attach machine;  
placing the base die on the substrate in the first die attach head so that a front side of the base die with bond pads faces toward the substrate and a backside of the base die faces away from the substrate;  
moving the base die to a second die attach head of the same die attach machine without heating the base die;  
stacking a first stacked die onto the base die in the second die attach head by dispensing an adhesive onto the backside of the base die and placing the first stacked die onto the adhesive in the second die attach head.

11. (Original) The method of claim 10, further comprising heating the base die and the first stacked die in a single heating cycle to secure the base die to the substrate and to secure the first stacked die to the base die.

12-47. (Cancelled)